

Title (en)

Method and apparatus for producing electrolytic copper foil.

Title (de)

Verfahren und Vorrichtung zur elektrolytischen Erzeugung von Kupferfolien.

Title (fr)

Procédé et dispositif pour la production d'une feuille de cuivre par électrodéposition.

Publication

EP 0491163 A1 19920624 (EN)

Application

EP 91119338 A 19911113

Priority

- JP 41176490 A 19901219
- JP 41176590 A 19901219
- JP 41176690 A 19901219

Abstract (en)

Method and apparatus of producing an electrolytic copper foil which comprises passing a stream of electrolyte between a rotating cathode (1) drum and at least one anode (3) facing the drum, effecting electrodeposition of copper on the surface of the cathode drum to form a copper foil, and thereafter peeling the foil from the drum, characterized in that the anode is at least partly divided into a plurality of sub-anodes for controlling foil thickness and that the foil thickness is uniformized or locally changed or modified as desired by controlling the individual foil thickness-controlling sub-anodes. The present invention is conducted on the basis of (A) control in the direction of the width, (B) control in the direction of the length, (C) control in the directions of the width and the length and (D) pattern control. The control is effected by controlling either the quantities of electricity supplied to the individual foil thickness-controlling sub-anodes or the individual set positions of the sub-anodes. <IMAGE>

IPC 1-7

C25D 1/04

IPC 8 full level

C25D 1/04 (2006.01)

CPC (source: EP KR)

C25D 1/04 (2013.01 - EP KR)

Citation (search report)

- [X] FR 2271306 A1 19751212 - MOSHIMA KOSAN CO LTD [JP]
- [A] US 3799847 A 19740326 - BOBROV A, et al

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CN104114751A; CN111194362A; CN106034404A; CN110616443A; US6071384A; EP0875605A3; US10309023B2; WO0177416A3; KR100568022B1

Designated contracting state (EPC)

DE FR GB LU SE

DOCDB simple family (publication)

EP 0491163 A1 19920624; EP 0491163 B1 19960214; DE 69117155 D1 19960328; DE 69117155 T2 19960905; KR 920012488 A 19920727; KR 940007609 B1 19940822; MY 138622 A 20090731

DOCDB simple family (application)

EP 91119338 A 19911113; DE 69117155 T 19911113; KR 910021865 A 19911130; MY PI9102092 A 19911113